

NOTES:

1. ALL DIMENSIONING AND TOLERANCES CONFORM TO ASME Y14.5-1994.
2. DATUM PLANE **Ⓛ** LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
- ⚠** DATUMS **ⓁⓂⓃ** AND **ⓓ** TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE **Ⓛ**.
- ⚠** LEADS DETERMINED AT LEAD TIP LOCATED AT DATUM PLANE **Ⓛ**.
- ⚠** DIMENSIONS **Ⓛ** AND **Ⓛ1** INCLUDE MOLD PROTRUSION.
- ⚠** ALLOWABLE MOLD PROTRUSION IS 0.254 MM PER SIDE.
- ⚠** DIMENSIONS **ⓓ** AND **ⓔ** INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE **Ⓛ**.
- ⚠** **Ⓝ** IS NUMBER OF TERMINALS.
- ⚠** PACKAGE TIP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS BY 0.10 MILLIMETERS. AND TOP OF PACKAGE WILL NOT OVERHANG BOTTOM OF PACKAGE.
- ⚠** DIMENSIONS **Ⓟ** DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM **Ⓟ** DIMENSION BY MORE THAN 0.08 MM. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
3. ALL DIMENSIONS ARE IN MILLIMETERS.
- ⚠** THE EXPOSED PAD IS COINCIDENT WITH THE TOP OR BOTTOM SIDE OF THE PACKAGE AND NOT ALLOWED TO PROTRUDE BEYOND THAT SURFACE.
- ⚠** THESE DIMENSIONS APPLY TO THE PLATE SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.20 MM FROM THE LEAD TIP.
12. THIS DRAWING CONFORMS TO JEDEC REGISTERED OUTLINE MS-026-C, VARIATION BFC AND BFC.
- ⚠** BUT THE EXPOSED PAD DIMENSION WAS NOT SPECIFIED ON JEDEC.
- ⚠** **Ⓛ1** IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- ⚠** DIMENSION **ⓓ2** AND **ⓔ** SHOW THE MINIMUM FILLING FOR THE EXPOSED PAD BETWEEN THE ALLOWED IS INSIDE OF JEDEC PINS IN ORDER NOT TO CONFLICT WITH THE PAD AND THE PAD CORNERS. HOWEVER, THE SIZE OF THE EXPOSED PAD IS VARIABLE DEPENDING ON DEVICE FUNCTION (DIE SIZE).
15. EXPOSED PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 0.05.
- ⚠** CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 0.30 MM.

(JEDEC VARIATION)				
ALL DIMENSIONS IN MILLIMETERS				
SYMBOL	BFC			NOMINAL
	MIN.	NDM.	MAX.	
A	↗	↗	1.20	13
A1	0.05	0.10	0.15	
A2	0.95	1.00	1.05	4
D	22.00 BSC.			
D1	20.00 BSC.			7,8
D2	2.00	↗	↗	10, 14
E	22.00 BSC.			4
E1	20.00 BSC.			7,8
E2	2.00	↗	↗	10, 14
L	0.45	0.60	0.75	
N	M128, 144			
e	0.50 BSC.			9
b	0.17	0.22	0.27	
b1	0.17	0.20	0.23	
ccc	↗	↗	0.08	
ddd	↗	↗	0.08	

(JEDEC VARIATION)					N T E
ALL DIMENSIONS IN MILLIMETERS					
S Y M B O L	BFC				
L	MIN.	NDM.	MAX.		
A			1.20	13	
A1	0.05	0.10	0.15		
A2	0.95	1.00	1.05		
D	22.00 BSC.			4	
D1	20.00 BSC.			7,8	
D2	2.00			10, 14	
E	22.00 BSC.			4	
E1	20.00 BSC.			7,8	
E2	2.00			10, 14	
L	0.45	0.60	0.75		
N	176 LD				
e	0.40 BSC.				
b	0.13	0.18	0.23	9	
b1	0.13	0.16	0.19		
ccc			0.08		
ddd			0.07		

■ NOTE: THE 128 LEAD IS A COMPLIANT DEPOPULATION OF THE 144 LEAD MS-026 VARIATION BFA.

Amkor Technology, Inc.
Chandler, Arizona, USA
Amkor Technology, Inc.
Chandler, Arizona, USA
Amkor Technology Philippines, Inc.
Makati, Philippines



PACKAGE OUTLINE, TOP, 20 X 20 MM BODY,
1.00/0.10 MM FORM, (PAD)

1.00 mm THICK (OPTIONAL, #PAD)

35909

04

PRINTING IS SCALED TO FIT

DO NOT SCALE DRAWING

1 : 1

2 OF 2

FORM NO. M0708M4JLVG